506619493 04/20/2021

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6666300

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TOMOHIRO TAKAHASHI	07/16/2020
NAOKI YOSHIMOCHI	02/08/2021
YOSHIAKI INADA	07/22/2020
MASATSUGU KOBAYASHI	07/15/2020
KOJI YODA	07/31/2020
TAKAHIRO IINUMA	03/25/2021

RECEIVING PARTY DATA

Name:	SONY SEMICONDUCTOR SOLUTIONS CORPORATION
Street Address:	4-14-1 ASAHI-CHO, ATSUGI-SHI
City:	KANAGAWA
State/Country:	JAPAN
Postal Code:	243-0014

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16761136

CORRESPONDENCE DATA

Fax Number: (414)277-0656

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 414-271-6560

Email: DCipdocket@michaelbest.com

MICHAEL BEST & FRIEDRICH LLP (SONY) **Correspondent Name:**

Address Line 1: 790 N WATER ST Address Line 2: **SUITE 2500**

Address Line 4: MILWAUKEE, WISCONSIN 53202

ATTORNEY DOCKET NUMBER:	880005-6592-US01
NAME OF SUBMITTER:	CHRISTOPHER M. TOBIN
SIGNATURE:	/Christopher M. Tobin/
DATE SIGNED:	04/20/2021
	This document serves as an Oath/Declaration (37 CFR 1.63).

PAIENI REEL: 055982 FRAME: 0011

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Total Attachments: 6 source=880005-6592-US01_Executed_Assignment#page1.tif source=880005-6592-US01_Executed_Assignment#page2.tif source=880005-6592-US01_Executed_Assignment#page3.tif source=880005-6592-US01_Executed_Assignment#page4.tif source=880005-6592-US01_Executed_Assignment#page5.tif source=880005-6592-US01_Executed_Assignment#page6.tif

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	TRANSMITTER		
As the below	named inventor, I hereby declare that:		
This declarati	The attraction method in the		
mai sessitutus esi	United States application or PCT international application number PCT/JP2018/031565 filed on 2018/08/27	····	
	entified application was made or authorized to be made by me.		
	I am the original inventor or an original joint inventor of a claimed invention in the application. SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with officer	s at	
***************************************	sahi-cho, Atsugi-shi, Kanagawa, Japan (hereimafter referred to as ASSIGNEE), is desirous		
	interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or simion which may be granted therefor in the United States and in any and all foreign countries;	ilar	
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;			
designee, as remaineration	r agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without furt, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent ates and countries foreign thereto;	her	
application for	er agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers or foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Lett may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;		
application,	er agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to staid invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and the same in any interference or litigation related thereto;		
And I hereby this assignment	covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict went and sale.	vith	
	nowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonmen n five (5) years, or both.	t of	
LEGAL NA	ME OF INVENTOR		
Inventor:	TOMOHIRO TAKAHASHI Date: Jul 16th, 2020		
Signature:	Fomohir Jakahashi		

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	TRANSMITTER	
As the below	low named inventor, I hereby declare that:	
This declarat is directed to	The attendered amplifaction are	
	United States application or PCT international application number PCT/. filed on 2018/08/27	P2018/031565
The above-id	e-identified application was made or authorized to be made by me.	
	that I am the original inventor or an original joint inventor of a claimed invention in the application as SONY SEMICONDUCTOR SOLUTIONS CORPORATION	
5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5		with offices at erred to as ASSIGNEE), is desirous of
acquiring all	all interest in, to and under said invention, said application disclosing the invention and in, to an extion which may be granted therefor in the United States and in any and all foreign countries;	
of which are logal represe in and to any any and all p Convention 1 adheres, and United State: Patent to said	HEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable come are hereby acknowledged. I by these presents do hereby assign, sell and transfer unto said ASS resentatives, the entire right, title and interest in said invention, said application, including any dividence and all Letters Patent of the United States, and countries foreign thereto, which may be graul priority rights and/or convention rights under the International Convention for the Protection on Relating to Patents, Designs and Industrial Models, and any other international agreements to and to any other henefits accruing or to accrue to me with respect to the filling of applications for tates and countries foreign thereto, and I hereby authorize and request the Commissioner of Patensaid ASSIGNEE, as the assignce of the whole right, title and interest thereto;	SIGNEE, its successors, assigns, and isions and continuations thereof, and sted for said invention, and in and to f Industrial Property, Inter-American which the United States of America patents or securing of patents in the its to issue said United States Letters
designee, as remuneration	rther agree to execute all necessary or desirable and lawful future documents, including assign as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time at order to perfect title in said invention, modifications, and improvements in said inventional States and countries foreign thereto;	present to me and without further
application (orther agree to properly execute and deliver and without further remuneration, such necessary on for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining laich may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require	any reissue or reissues of any Letters
application,	wher agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent ton, said invention and said Letters Patent and legal equivalents in foreign countries as may be to the same in any interference or litigation related thereto;	
5 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	reby covenant that no assignment, sale, agreement or encumbrance has been or will be made or express and sale.	stered into which would conflict with
	acknowledge that any willful false statement made in this declaration is punishable under 18 U.5 than five (5) years, or both.	s.C. 1001 by fine or imprisonment of
LEGAL NA	NAME OF INVENTOR	
Inventor:	YOSHIAKI INADA Date: J	1, 22,46,3020
Signature:	* YOSHIAKI INADA	

Attorney Docket No.: Sony Ref. No.: SP371041US00

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	TRANSMITTER		
As the below	named inventor, I hereby declare that:		
This declarati	The attacked annihilation of		
	United States application or PCT international application number PCT/JP2018/031565 filed on 2018/08/27		
	ientified application was made or authorized to be made by me.		
	A am the original inventor or an original joint inventor of a claimed invention in the application. SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at		
4-14-1 A	sahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of		
	interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar on which may be granted therefor in the United States and in any and all foreign countries;		
NOW THEREPORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convemion rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;			
designee, as remuneration	r agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further it, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of tates and countries foreign thereto:		
application for	er agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for or foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense:		
application,	er agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will the same in any interference or litigation related thereto;		
And I hereby this assignme	covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with ent and sale.		
	nowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of n five (5) years, or both.		
LEGAL NA	ME OF INVENTOR		
Inventor:	MASATSUGU KOBAYASHI Date: 2020 / 7 / 15		
Signature:	Masatsugu kebuyashi		

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	TRANSMITTER	
As the below	named inventor, I hereby declare that:	
This declarati	1 1 Who considered mark hearings as 2	
	United States application or PCT international application number PCT/JP2018/031565 filed on 2018/08/27	
	entified application was made or authorized to be made by me.	
	Tam the original inventor or an original joint inventor of a claimed invention in the application. SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at	
4-14-1 A	sahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of	
	interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar on which may be granted therefor in the United States and in any and all foreign countries;	
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;		
designee, as remuneration	r agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further i, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of lates and countries foreign thereto:	
application for	er agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for or foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;	
application,	er agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said said invention and said Letters Patent and logal equivalents in foreign countries as may be known and accessible to me and will be same in any interference or litigation related thereto;	
And I hereby this assignment	covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with ent and sale.	
	nowledge that any willful false statement made in this declaration is puntshable under 18 U.S.C. 1001 by fine or imprisonment of n five (5) years, or both.	
LEGAL NA	ME OF INVENTOR	
Inventor:	KOJI YODA Date: 2020 / 7 / 3	
Signature:	Koji Yoda	

Attorney Docket No.: Sony Ref. No.: SP371041US00

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention	TRANSMITTER		
As the below	named inventor, I hereby declare that:		
This declarati	This declaration is directed to: The attached application, or		
	United States application or PCT international application number		
The above-ide	entified application was made or authorized to be made by me.		
WHEREAS,	I am the original inventor or an original joint inventor of a claimed invention in the application. SONY SEMICONDUCTOR SOLUTIONS CORPORATION , with offices at		
4-14-1 A	sahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of		
acquiring all legal protection	interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar on which may be granted therefor in the United States and in any and all foreign countries;		
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;			
And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;			
And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;			
And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;			
And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.			
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.			
LEGAL NAN	ME OF INVENTOR		
Inventor:	NAOKI YOSHIMOCHI Date: 2021/02/08		
Signature:	/Naoki Yoshimochi/		

Attorney Docket No.: Sony Ref. No.: SP371041US00

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

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	United States application or PCT international application number PCT/JP2018/031565 filed on 2018/08/27		
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acquiring all	sahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar on which may be granted therefor in the United States and in any and all foreign countries;		
NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;			
designee, as remuneration	And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;		
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I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.			
LEGAL NAN	ME OF INVENTOR		
Inventor:	TAKAHIRO IINUMA Date: 2021/03/25		
Signature: _	/Takahiro Iinuma/		

RECORDED: 04/20/2021